



- PIV to 200 Volts
- Extremely Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Surge Capacity
- Possible Replacement for 1N5802 - 1N5806 Series
- Hermetically Sealed
- For low voltage versions, see data sheet RS0006
- TX, TXV, and Space Level Screening Available^{2/}
- Category III metallurgical bond per MIL-PRF-19500 appendix A

$$\begin{aligned} 1502 &= 150 \text{ V} \\ 2002 &= 200 \text{ V} \end{aligned}$$

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SPD1502 thru SPD2002 Series

Electrical Characteristic		Symbol	Min	Max	Units
Instantaneous Forward Voltage Drop ($T_J = 25^\circ\text{C}$, 300 - 500 μsec pulse)	$I_F = 0.5\text{A}$	V_{F1}	---	0.78	Volts
	$I_F = 1\text{A}$	V_{F2}	---	0.85	
	$I_F = 2\text{A}$	V_{F3}	---	0.95	
Instantaneous Forward Voltage Drop ($I_F = 1\text{A}$, 300 - 500 μsec pulse)	$T_A = -55^\circ\text{C}$	V_{F4}	---	1.10	Volts
	$T_A = 100^\circ\text{C}$	V_{F5}	---	0.78	
Reverse Leakage Current ($V_R = \text{Rated } V_R$, $T_A = 25^\circ\text{C}$, 300 μsec min pulse)		I_{R1}	---	100	μA
Reverse Leakage Current ($V_R = \text{Rated } V_R$, $T_A = 100^\circ\text{C}$, 300 μsec min pulse)		I_{R2}	---	2	mA
Junction Capacitance ($V_R = 10\text{ Vdc}$, $T_A = 25^\circ\text{C}$, $f = 1\text{MHz}$)		C_J	---	40	pF

Consult manufacturing for operating curves

CASE OUTLINE: Axial Lead	DIMENSIONS		
	DIM	MIN	MAX
	A	0.155"	0.185"
	B	0.080"	0.107"
	C	1.00"	--
	D	0.028"	0.032"
CASE OUTLINE: Surface Mount Round Tab (SM)	DIMENSIONS		
	DIM	MIN	MAX
	A	0.095"	0.105"
	B	0.190"	0.210"
	C	0.015"	0.025"
	D	0.002"	--
CASE OUTLINE: Surface Mount Square Tab (SMS)	DIMENSIONS		
	DIM	MIN	MAX
	A	0.200"	0.235"
	B	0.125"	0.135"
	C	0.020"	0.030"
	D	0.002"	--

Dimensions prior to solder dip

NOTE: All specifications are subject to change without notification.
SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: SH0077B

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